

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2657812

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>U-TING CHEN</td> <td>12/04/2013</td> </tr> <tr> <td>SHU-TING TSAI</td> <td>12/04/2013</td> </tr> <tr> <td>SZU-YING CHEN</td> <td>12/16/2013</td> </tr> <tr> <td>JENG-SHYAN LIN</td> <td>12/04/2013</td> </tr> <tr> <td>DUN-NIAN YAUNG</td> <td>12/05/2013</td> </tr> <tr> <td>JEN-CHENG LIU</td> <td>12/05/2013</td> </tr> </tbody> </table>		Name	Execution Date	U-TING CHEN	12/04/2013	SHU-TING TSAI	12/04/2013	SZU-YING CHEN	12/16/2013	JENG-SHYAN LIN	12/04/2013	DUN-NIAN YAUNG	12/05/2013	JEN-CHENG LIU	12/05/2013
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77		
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Application Number:	14133387														
CORRESPONDENCE DATA															
Fax Number:	(972)732-9218														
Phone:	972-732-1001														
Email:	docketing@slater-matsil.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	SLATER & MATSIL, L.L.P.														
Address Line 1:	17950 PRESTON ROAD														
Address Line 2:	SUITE 1000														
Address Line 4:	DALLAS, TEXAS 75252														
ATTORNEY DOCKET NUMBER:	TSM13-0996														

PATENT

NAME OF SUBMITTER:	SHERRY L. COLGROVE
Signature:	/SHERRY L COLGROVE/
Date:	12/20/2013
Total Attachments: 2 source=TSM13-0996_Assignment#page1.tif source=TSM13-0996_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Image Sensor Devices, Methods of Manufacture Thereof, and Semiconductor Device Manufacturing Methods			
SIGNATURE OF INVENTOR AND NAME	<input checked="" type="checkbox"/> U-Ting Chen U-Ting Chen	<input checked="" type="checkbox"/> Shu-Ting Tsai Shu-Ting Tsai	<input checked="" type="checkbox"/> Szu-Ying Chen Szu-Ying Chen	<input checked="" type="checkbox"/> Jeng-Shyan Lin Jeng-Shyan Lin
DATE	<input checked="" type="checkbox"/> 2013.12.4	<input checked="" type="checkbox"/> 2013.12.4	<input checked="" type="checkbox"/> 2013/12/16	<input checked="" type="checkbox"/> 2013.12.4
RESIDENCE	Wanluan Township, Taiwan	Kaohsiung City, Taiwan	Toufen Township, Taiwan	Tainan City, Taiwan

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WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

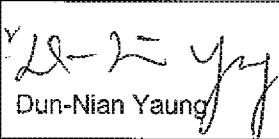
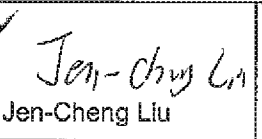
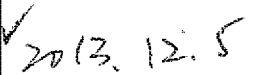
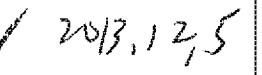
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

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TITLE OF INVENTION	Image Sensor Devices, Methods of Manufacture Thereof, and Semiconductor Device Manufacturing Methods			
SIGNATURE OF INVENTOR AND NAME	 Dun-Nian Yaung	 Jen-Cheng Liu		
DATE	 2013.12.5	 2013.12.5		
RESIDENCE	Taipei City, Taiwan	Hsin-chu, Taiwan		